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(54) Title: CONTROL OF WAFER BOW DURING INTEGRATED CIRCUIT PROCESSING

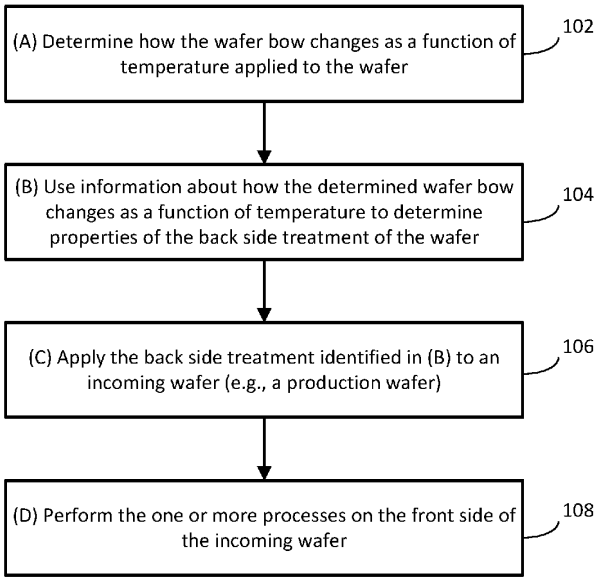

Figure 1

(57) Abstract: A method of controlling wafer bow in an integrated circuit fabrication process may include characterizing the wafer bow in response to performing one or more first fabrication processes to an active side of an integrated circuit wafer. Determining one or more second fabrication processes, to be applied to a back side of the integrated circuit wafer, to bring the wafer bow to below a predetermined threshold based on the one or more first fabrication processes the method may additionally include performing the one or more second fabrication processes on the back side of the integrated circuit wafer.

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